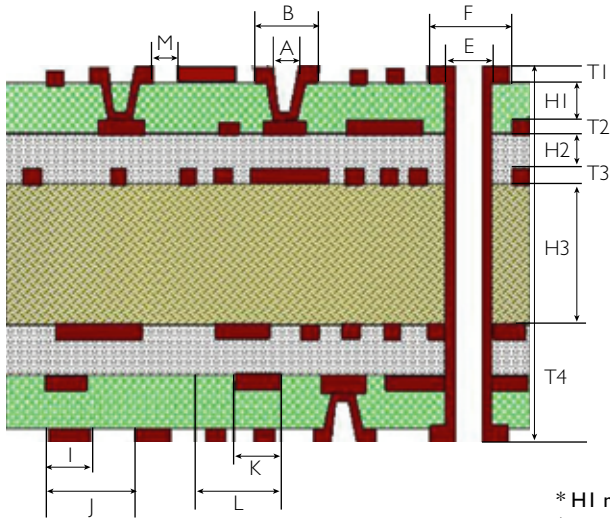


'A' Type Build-Up PCB

- (1) Spec : 6L , 1.6T , ENIG , Micro via (1~2L, 5~6L, 1~6L Via)
- (2) Stack-up



* H1 material : RCC , LDP

* H2, H3 material : FR - 4

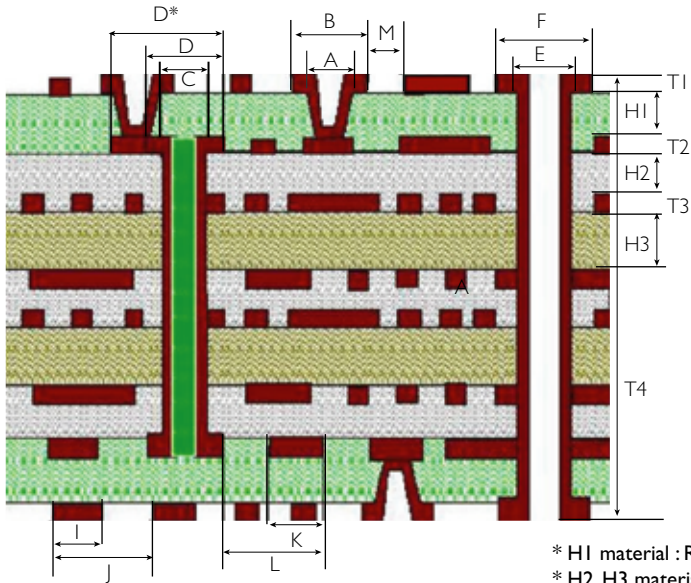
ITEM#	Division	MASS	PROTO
A	Via size (Laser)	100 ~ 130 μ m	100 μ m
B	Via Land (Laser)	250 ~ 350 μ m	250 μ m
E	PTH((Plated Thru Hole) Size	200 ~ 300 μ m	200 μ m
F	PTH((Plated Thru Hole) Land	450 ~ 550 μ m	400 μ m
I	Outer Line Width	75 ~ μ m	70 μ m
J	Outer Line Pitch	150 ~ μ m	150 μ m
K	Inner Line Width	100 ~ μ m	80 μ m
L	Inner Line Pitch	150 ~ μ m	150 μ m
M	Copper Fill Space	180 ~ μ m	150 ~ μ m
H1	1-2L Resin Thickness	60 ~ 80 μ m	60 μ m
H2	2-3L Resin Thickness	100 ~ 500 μ m	100 μ m
H3	3-4L Resin Thickness	100 ~ μ m	100 μ m
T1	1L CU Thickness	32 ~ 42 μ m	30 μ m
T2	2L CU Thickness	30 ~ 42 μ m	30 μ m
T3	3L CU Thickness	30 ~ 42 μ m	30 μ m
T4	Total Thickness	400 ~ μ m	400 μ m
Layer		4~14 L	16 L

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'B' Type Build-Up PCB

- (1) Spec : 8L , 1.6T , ENIG , Micro via (1~2L, 2~7L, 7~8L, 1~8L Via)
- (2) Stack-up



* H1 material : RCC

* H2, H3 material : FR - 4

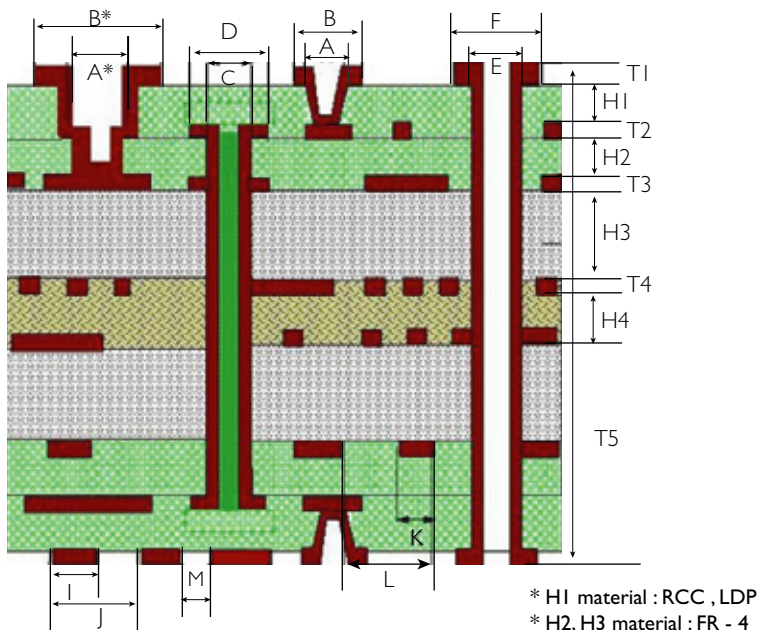
ITEM#	Division	MASS	PROTO
A	Via size (Laser)	100 ~ 130 μ m	100 μ m
B	Via Land (Laser)	250 ~ 350 μ m	250 μ m
C	Inner Via Size	200 ~ 250 μ m	200 μ m
D*	Inner Via Land	450 ~ 550 μ m	400 μ m
D	Step Land	700 ~ 900 μ m	600 μ m
E	PTH((Plated Thru Hole) Size	200 ~ 300 μ m	200 μ m
F	PTH((Plated Thru Hole) Land	450 ~ 550 μ m	400 μ m
I	Outer Line Width	75 ~ μ m	75 μ m
J	Outer Line Pitch	150 ~ μ m	150 μ m
K	Inner Line Width	75 ~ μ m	75 μ m
L	Inner Line Pitch	150 ~ μ m	150 μ m
M	Copper Fill Space	150 ~ μ m	150 ~ μ m
H1	1-2L Resin Thickness	60 ~ 80 μ m	60 μ m
H2	2-3L Resin Thickness	60 ~ 180 μ m	60 μ m
H3	3-4L Resin Thickness	100 ~ μ m	100 μ m
T1	1L CU Thickness	32 ~ 42 μ m	30 μ m
T2	2L CU Thickness	30 ~ 42 μ m	30 μ m
T3	3L CU Thickness	30 ~ 42 μ m	30 μ m
T4	Total Thickness	600 ~ μ m	600 μ m
Layer		4~14 L	16 L

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'C' Type Build-Up PCB

- (1) Spec : 8L , 1.6T , ENIG , Micro via (1~2L, 2~3L, 2~7L, 7~8L, 1~8L Via)
- (2) Stack-up



ITEM#	Division	MASS	PROTO
A*	Double Via Size	100 ~ 130 μ m	100 μ m
B*	Double Via Land	250 ~ 350 μ m	250 μ m
A	Via size (Laser)	100 ~ 130 μ m	100 μ m
B	Via Land (Laser)	300 ~ 350 μ m	300 μ m
C	Inner Via Size	200 ~ 250 μ m	200 μ m
D	Inner Via Land	450 ~ 550 μ m	400 μ m
E	PTH((Plated Thru Hole) Size	200 ~ 300 μ m	200 μ m
F	PTH((Plated Thru Hole) Land	450 ~ 550 μ m	400 μ m
I	Outer Line Width	75 ~ μ m	75 μ m
J	Outer Line Pitch	150 ~ μ m	150 μ m
K	Inner Line Width	75 ~ μ m	75 μ m
L	Inner Line Pitch	150 ~ μ m	150 μ m
M	Copper Fill Space	150 ~ μ m	150 ~ μ m
H1	1-2L Resin Thickness	60 ~ 80 μ m	60 μ m
H2	2-3L Resin Thickness	60 ~ 80 μ m	60 μ m
H3	3-4L Resin Thickness	100 ~ μ m	100 μ m
H4	4-5L Resin Thickness	100 ~ 180 μ m	100 μ m
T1	1L CU Thickness	32 ~ 60 μ m	30 μ m
T2	2L CU Thickness	30 ~ 60 μ m	30 μ m
T3	3L CU Thickness	18 ~ 35 μ m	30 μ m
T5	Total Thickness	1000 ~ μ m	1000 μ m
	Layer	6~14 L	16 L

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